

Supplementary Information for

**Aluminium and Zinc co-doped CuInS<sub>2</sub> QDs for enhanced  
trion modulation in monolayer WS<sub>2</sub> toward improved  
electrical properties**

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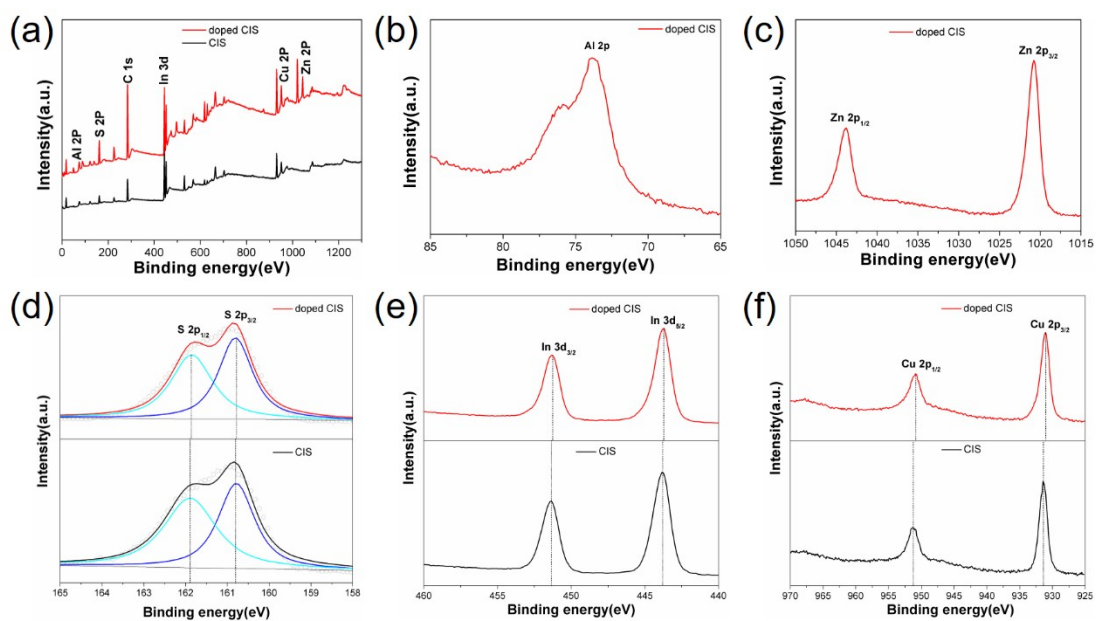


Fig. S1 (a) Full spectra of CIS and doped CIS QDs; (b) Al 2p and (c) Zn 2p spectra of doped CIS QDs; The comparison of Cu 2p (d), S 2p (e) and In 3d (f) spectra in CIS and doped-CIS QDs.

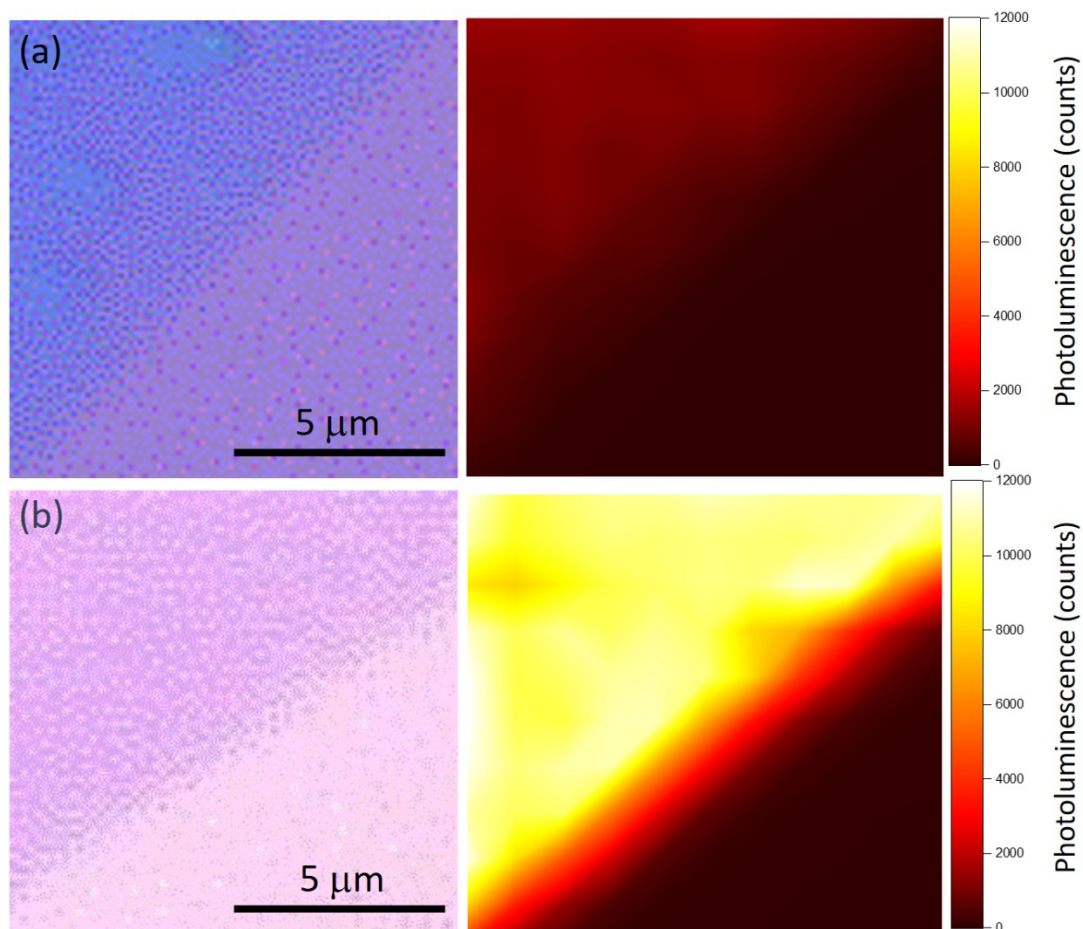
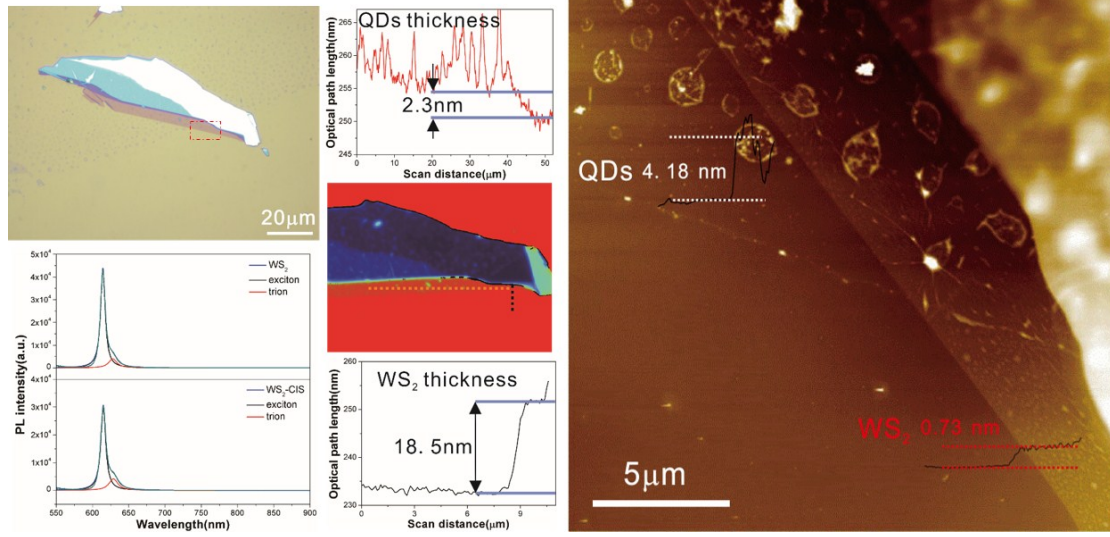


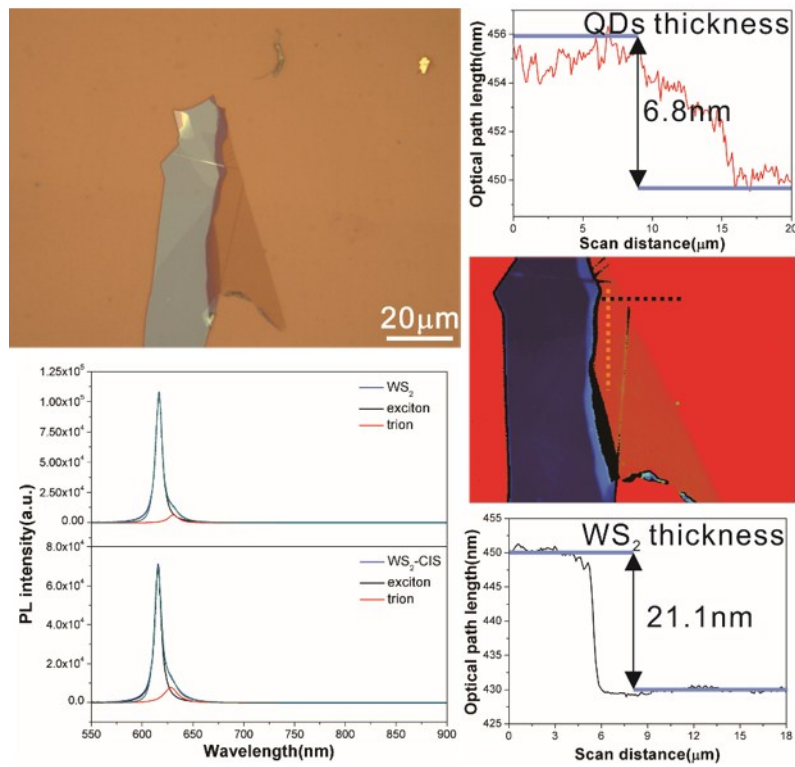
Fig. S2. The optical image and corresponding PL intensity mapping results of (a) CIS QDs and (b)

doped CIS QDs.

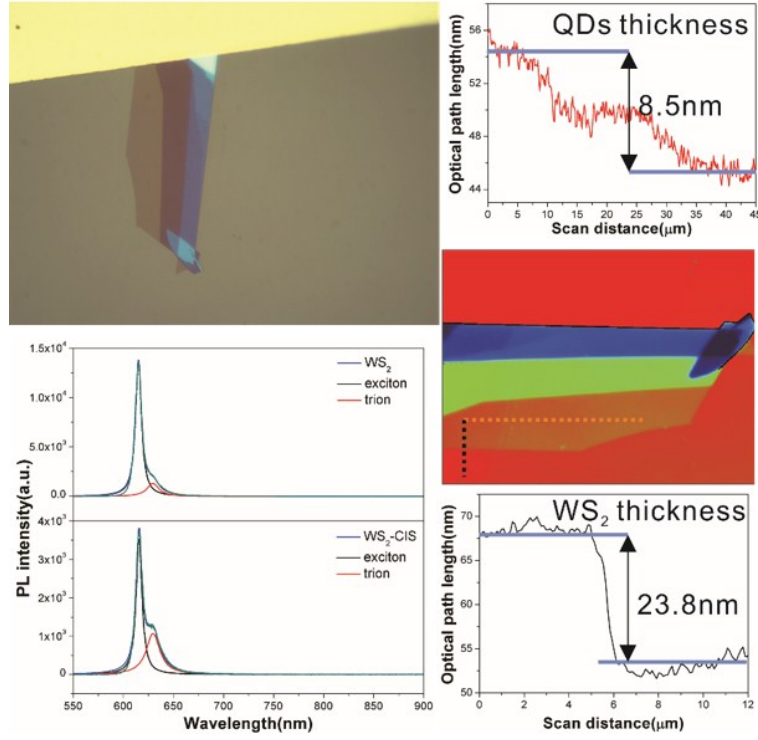
### The first CIS QDs thickness



### The second CIS QDs thickness



### The third CIS QDs thickness



### The fourth CIS QDs thickness

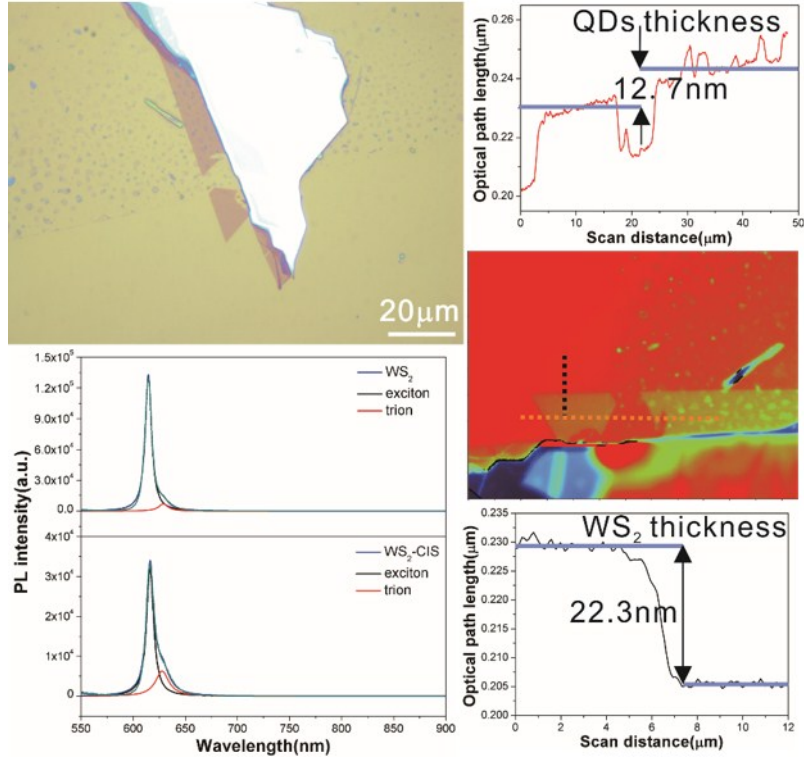
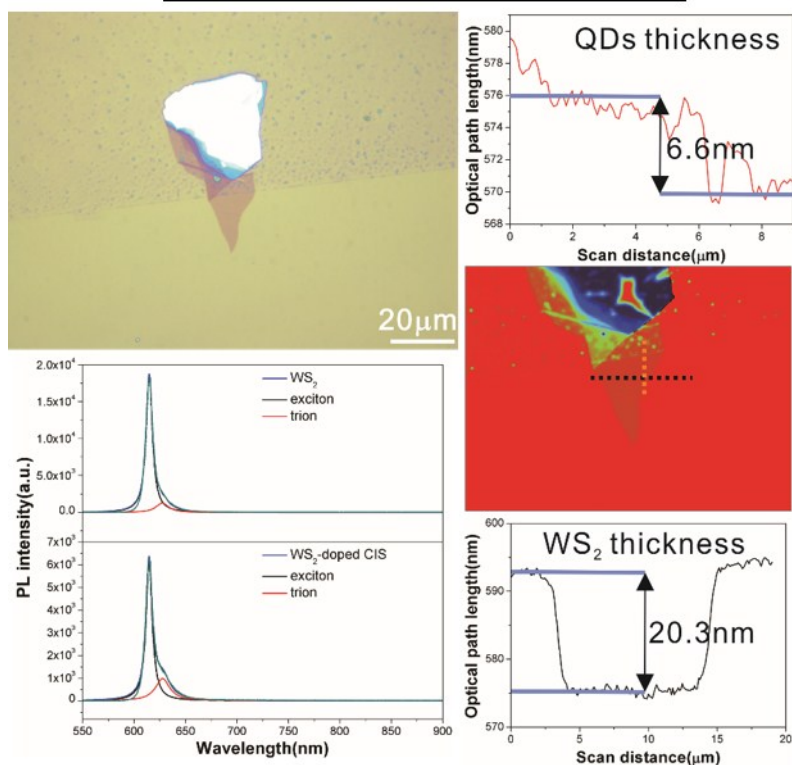


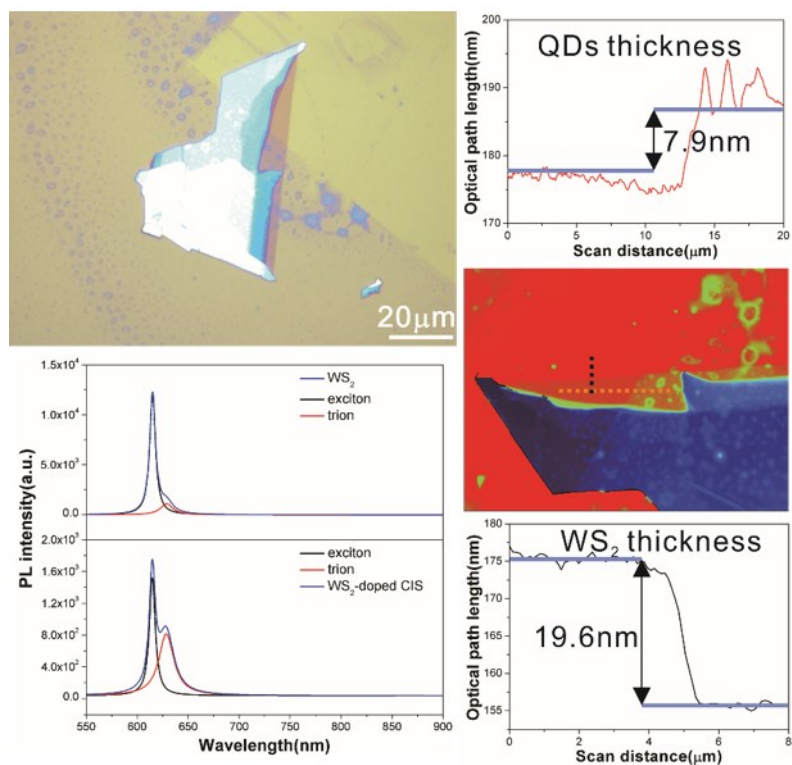
Fig. S3. The fabricated WS<sub>2</sub>-CIS chips with different CIS QDs thickness, including optical image, PSI measurement, and the corresponding PL spectra without and with CIS QDs modification. The CIS QDs thickness is in the range of 2.3 to 12.7 nm. It should be noted that OPL value of 2.3 in first

CIS QDs thin film correspond to 4.18 nm actual CIS thickness, and OPL value of 18.5 nm in bare  $\text{WS}_2$  correspond to the actual 0.73 nm thickness of monolayer  $\text{WS}_2$ .

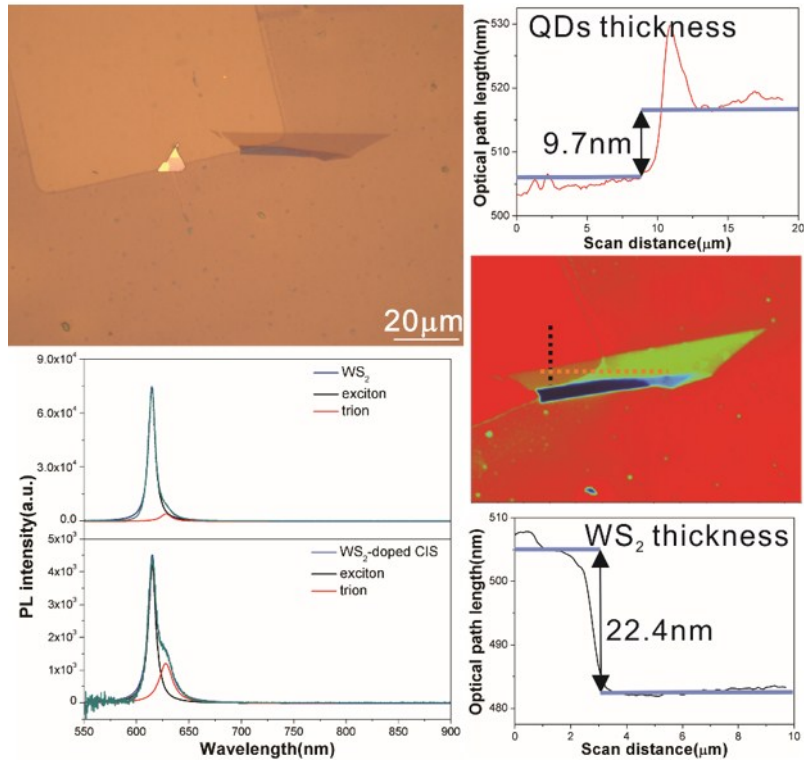
### The first doped-CIS QDs thickness



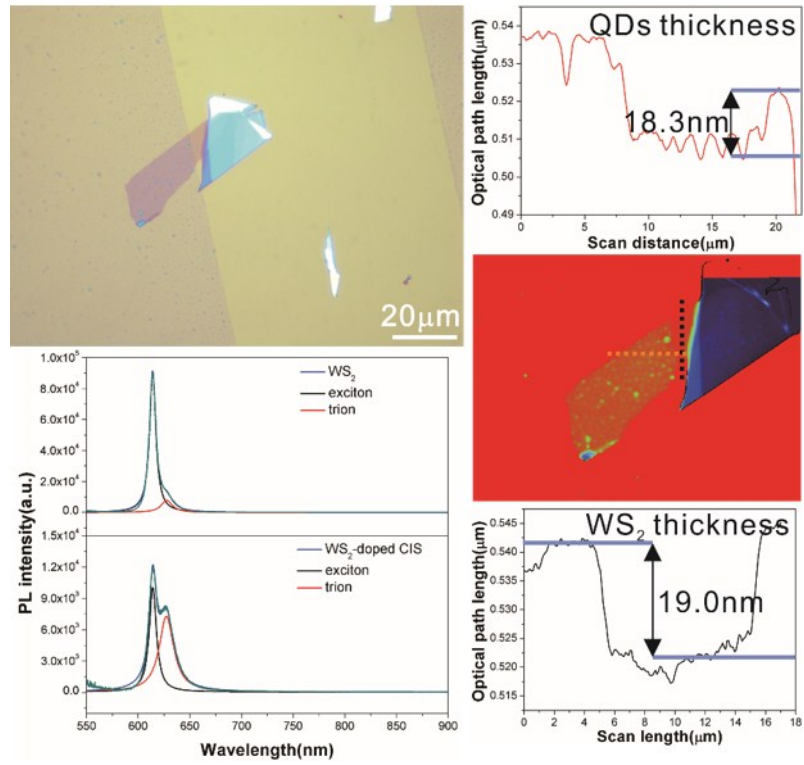
### The second doped-CIS QDs thickness



### The third doped-CIS QDs thickness



### The fourth doped-CIS QDs thickness



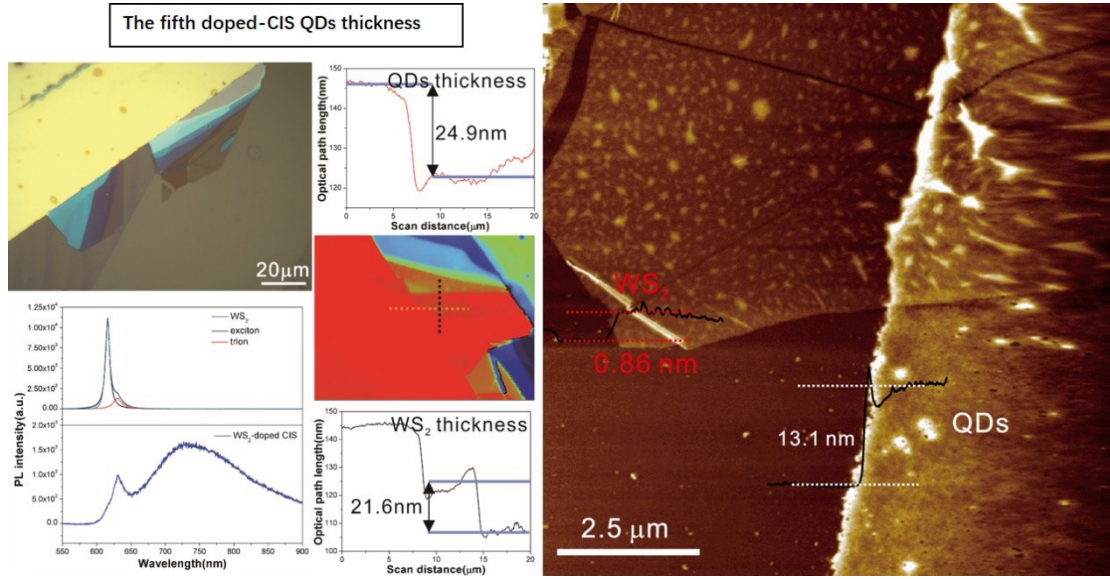


Fig. S4. The fabricated  $\text{WS}_2$ -doped CIS chips with different doped CIS QDs thickness, including optical image, PSI measurement, and the corresponding PL spectra without and with doped-CIS QDs modification. The doped-CIS QDs thickness is in the range of 6.6 to 24.9 nm. It should be noted that OPL value of 24.9 in fifth doped-CIS QDs correspond to 13.1 nm actual doped-CIS thickness, and OPL value of 21.6 nm in bare  $\text{WS}_2$  correspond to the actual 0.86 nm thickness of monolayer  $\text{WS}_2$ .

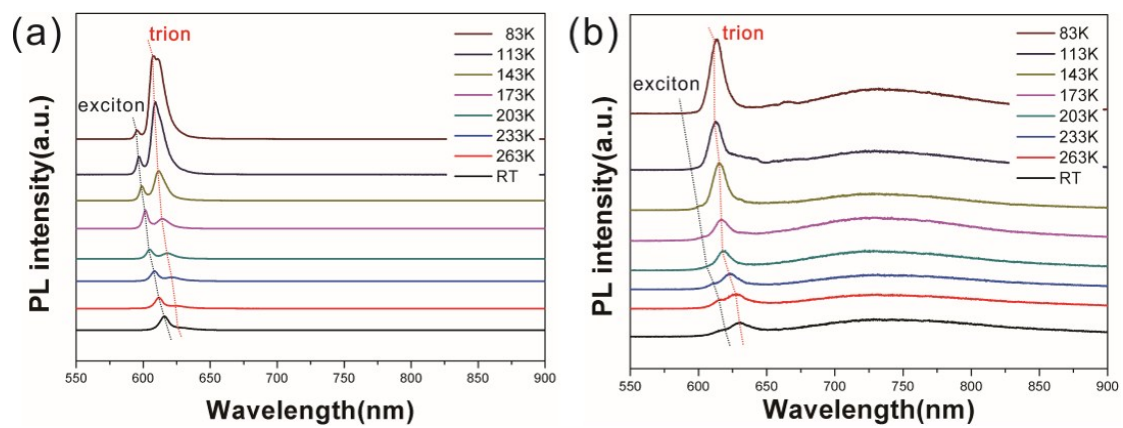


Fig. S5. Temperature-dependent PL spectra of (a) bare WS<sub>2</sub> and (b) WS<sub>2</sub>-doped CIS with 24.9 nm QDs thickness. (the fifth doped-CIS thickness)

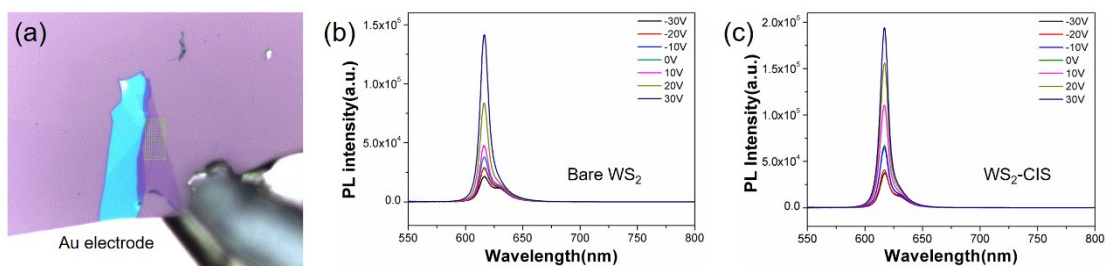


Fig. S6. (a) Optical image of WS<sub>2</sub>-CIS for gate-dependent testing. (b) PL spectra of bare WS<sub>2</sub> under different gate voltage. (c) PL spectra of WS<sub>2</sub>-CIS under different gate voltage.

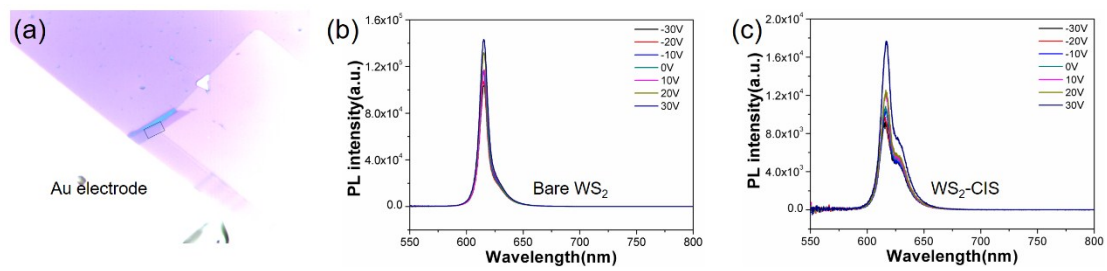


Fig. S7. (a) Optical image of WS<sub>2</sub>-doped CIS for gate-dependent testing. (b) PL spectra of bare WS<sub>2</sub> under different gate voltage. (c) PL spectra of WS<sub>2</sub>-CIS under different gate voltage.

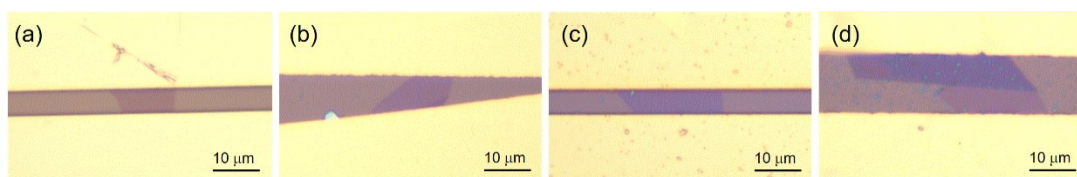


Fig. S8. Optical images of as-fabricated FET chips. (a) bare WS<sub>2</sub>; (b) WS<sub>2</sub>-CIS; (c) WS<sub>2</sub>-doped CIS 1; (d) WS<sub>2</sub>-doped CIS 2.